



TG-996-1

Ultra-Soft Silicone Thermal Pad

Version 2.130218

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TG-996-1 is an ultra-soft, silicone based thermal gap filler which offers low thermal impedance, good surface compliance and a high dielectric breakdown voltage. TG-996-1 can be supplied in a wide range of formats ranging from custom die cut parts to standard sheets in a range of thicknesses depending on the end application.

Applications

Soft silicone based thermal interface material or heat sink to dissipate the heat from electronic devices, especially in integrated circuit (IC) device and LEDs packaging.

Properties

- ✓ REACH Compliant
- ✓ ROHS Compliant

Property	TG-996-1 Unit		Test Method
Binder	Silicone	-	-
Colour	White	-	Visual
Reinforcement	None	-	-
Specific gravity	2.2	-	-
Thermal Conductivity	1.5	Wm ⁻¹ K ⁻¹	ASTM D5470
Hardness	35	Shore 00	ASTM D2240
Surface Tacky	Both Sides Tacky	-	-
Flammability	V-0	-	UL 94
Shelf Life	36	months	-
Shelf Life with adhesive (can be requalified for further 12)	12	months	-

Part Number Information

Product	Length	Width	Thickness	Adhesive
TG-996-1	288mm	192mm	0.5-8.0mm	Option available

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